

Title (en)

PLASMA SPUTTERING PROCESS FOR PRODUCING PARTICLES

Title (de)

PLASMA-SPUTTERINGVERFAHREN ZUR HERSTELLUNG VON PARTIKELN

Title (fr)

PROCÉDÉ DE PULVÉRISATION CATHODIQUE SOUS PLASMA POUR LA PRODUCTION DE PARTICULES

Publication

EP 2539480 A1 20130102 (EN)

Application

EP 11747794 A 20110222

Priority

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- SE 2011050201 W 20110222

Abstract (en)

[origin: WO2011105957A1] A high production rate plasma sputtering process for producing particles having a size of 10 µm or less is disclosed. The process causes ionization of at least a part of the sputtered target atoms and is performed at such parameters that the pick-up probability of ionized sputtered target atoms on the surface of grains is high.

IPC 8 full level

B22F 9/12 (2006.01); **C23C 14/22** (2006.01); **C23C 14/34** (2006.01); **H01J 37/34** (2006.01)

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DOCDB simple family (publication)

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